

TIF™ 035-05 is a soft silicone putty thermal gap filler, which blends with exclusive formula, that offers superior thermal performance, and compressibility.

Due to **TIF™ 035-05** is made by high viscosity silicon oil, that can prevent thermal formula separate from it. Besides, compared with traditionally thermal pad, it can control bonded shifting issue much better.

TIF™ 035-05 operation mold is similar as grease, such as silkprint and screen print or automatic injected facility.

TIF™ 035-05 can be applied on chip micro processor, PPGAs, Micro BGA package, BGA package, DSP chip, LED lighting and other high power electric component.

Feature

- › Thermal conductivity: **3.5 W/mK**
- › Soft, very low compression
- › Low thermal impedance
- › Operate automatically
- › Proven long-term reliability

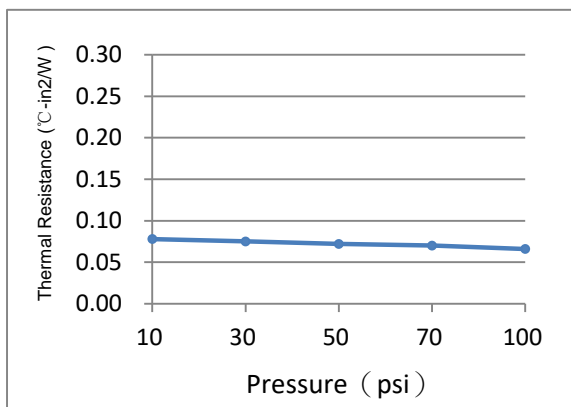
Application

- › Heat-sink & frame
- › LED backlight module · LED lighting
- › High speed hardware driver
- › Micro heat pipe › Vehicel engine controller
- › Telecom industry › Semiconductor automatic laboratory equipment.

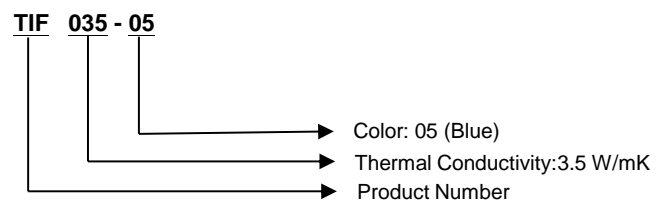
TIF™035-05 Property

| Property | Value | Standard |
|-------------------------------|---------------------------------|-------------|
| Color | Blue | Visual |
| Construction & Composition | Ceramic filled silicon material | ***** |
| Viscosity | 2000,000cps | GB/T 10247 |
| Specific Gravity | 3.0 g/cc | ASTM D297 |
| Thermal conductivity | 3.5 W/mK | ISO 22007-2 |
| Thermal diffusivity | 1.1073 mm ² /s | ISO 22007-2 |
| Specific heat capacity | 3.3 MJ/m ³ K | ISO 22007-2 |
| Continuous Use Temperature | -45 ~200°C | ***** |
| Dielectric breakdown strength | 200 V/mil | ASTM D149 |
| Flame Rating | 94V0 | E331100 |
| Outgassing, %TML | 0.80% | ASTM E595 |

psi. vs. Thermal Resistance



Product Identification:



Product Specification:

•30 cc/pc, 98 pc/box; 300 cc/pc 6 pc/box

We offer the custom packaged in syringes for automated dispensing applications. Please contact us for confirming.

If you want to know our thermal Products, you can visit our website : <http://www.ziitek.com>



Gap Fillers | Pouring sealant | Silicon tape | Thermally Conductive paste | Flake graphite | Thermally Conductive Insulators | Shielding Materials
Thermally Conductive plastic | Thermally Conductive Adhesive Tapes

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